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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/706,156	11/12/2003	Tai-Chun Huang	TSM03-0340	7569	
25962	7590 06/02/2006	·	EXAM	INER	
SLATER & MATSIL, L.L.P. 17950 PRESTON RD, SUITE 1000			OWENS, DOUGLAS W		
	X 75252-5793		ART UNIT PAPER NUMBER		
			2811	-	
			DATE MAILED: 06/02/2004	DATE MAILED: 06/02/2006	

Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)				
		10/706,156	HUANG ET AL.				
	Office Action Summary	Examiner	Art Unit				
_		Douglas W. Owens	2811				
Period fo	The MAILING DATE of this communication apport Reply	ears on the cover sheet with the o	orrespondence address				
WHIC - Exte after - If NC - Failu Any	ORTENED STATUTORY PERIOD FOR REPLY CHEVER IS LONGER, FROM THE MAILING DATES OF THE MAILING THE M	ATE OF THIS COMMUNICATION 36(a). In no event, however, may a reply be tir vill apply and will expire SIX (6) MONTHS from , cause the application to become ABANDONE	N. mely filed the mailing date of this communicatio (D) (35 U.S.C. § 133).				
Status							
1)⊠	Responsive to communication(s) filed on 15 M	arch 2006.					
2a)⊠	This action is FINAL . 2b) This action is non-final.						
3)	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is						
	closed in accordance with the practice under E	Ex parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.				
Disposit	ion of Claims						
4)⊠	Claim(s) 1-59 is/are pending in the application.						
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5)🖂	Claim(s) <u>8-51 and 56-59</u> is/are allowed.						
6)🖂	6)⊠ Claim(s) <u>1,4-6,52 and 54</u> is/are rejected.						
•	Claim(s) <u>2,3,7,53 and 55</u> is/are objected to.						
8)[]	Claim(s) are subject to restriction and/o	r election requirement.					
Applicat	ion Papers						
9)	The specification is objected to by the Examine	ır.					
10)	The drawing(s) filed on is/are: a) acc	epted or b) objected to by the	Examiner.				
	Applicant may not request that any objection to the	drawing(s) be held in abeyance. Se	e 37 CFR 1.85(a).				
	Replacement drawing sheet(s) including the correct			d).			
11)	The oath or declaration is objected to by the Ex	caminer. Note the attached Office	Action or form PTO-152.				
Priority (under 35 U.S.C. § 119						
	Acknowledgment is made of a claim for foreign All b) Some * c) None of:	priority under 35 U.S.C. § 119(a)-(d) or (f).				
,	1. Certified copies of the priority document	s have been received.					
	2. Certified copies of the priority document	s have been received in Applicat	ion No				
	3. Copies of the certified copies of the prio	rity documents have been receive	ed in this National Stage				
	application from the International Burea						
* (See the attached detailed Office action for a list	of the certified copies not receive	∍d.				
Attachmer							
	ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948)	4) Interview Summary Paper No(s)/Mail D					
3) 🔲 Infor	rmation Disclosure Statement(s) (PTO-1449 or PTO/SB/08) er No(s)/Mail Date		Patent Application (PTO-152)				

DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

- (b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.
- 2. Claims 1, 4 6, 52 and 54 are rejected under 35 U.S.C. 102(b) as being anticipated by US Patent No. 6,069,400 to Kimura et al.

Regarding claim 1, Kimura et al. teach a method of manufacturing an inter-level dielectric layer of a semiconductor device (Figs. 4 and 23, for example), the method comprising:

forming an etch-stop layer (17) over a substrate;

forming a first low-dielectric constant material sub-layer (5f) over the substrate, the first low-dielectric constant material having at least one first material property;

forming a second low-dielectric constant material sub-layer (3) over the first low-dielectric constant material sub-layer, the second low-dielectric constant material sub-layer having at least one second material property, wherein the at least one second material property is different from the at least one first material property; and

forming a third low-dielectric constant material sub-layer (6f) over the second low-dielectric constant material sub-layer, the third low-dielectric constant material sub-layer having at least one third material property, the at least one third material property being different from the at least one second material property, wherein the first low-

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dielectric constant material sub-layer, the second low-dielectric constant material sublayer, and the third low-dielectric constant material sub-layer form a single ILD layer.

Regarding claim 4, Kimura et al. inherently teach a method, wherein manufacturing the ILD layer comprises forming the first low-dielectric constant material sub-layer, second low-dielectric constant material sub-layer, and third low-dielectric constant material sub-layer while adjusting the deposition conditions. The different material layers require adjusting deposition conditions.

Regarding claim 5, Kimura et al. inherently teach a method, wherein adjusting the deposition conditions comprises adjusting the power, since deposition of each layer would require different power.

Regarding claims 6 and 54, Kimura et al. teach a product and method wherein the first material property, second material property and third material property comprise density and dielectric constant.

Regarding claim 52, Kimura et al. teach an inter-level layer of a semiconductor device, comprising:

a first low-dielectric constant material sub-layer (5f), the first low-dielectric constant material having at least one first material property;

a second low-dielectric constant material sub-layer (3) disposed over the first low-dielectric constant material sub-layer, the second low-dielectric constant material sub-layer having at least one second material property, wherein the at least one second material property is different from the at least one first material property; and

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a third low-dielectric constant material sub-layer disposed over the second low dielectric constant material sub-layer, the third low-dielectric constant material sub-layer having at lest one third material property, the at least one third material property being different from the at least one second material property, wherein the first low-dielectric constant material sub-layer, the second low-dielectric material sub-layer, and the third low-dielectric constant material sub-layer form a single ILD layer.

With respect to the requirement that first, second and third sub-layers be formed continuously from the same material in one or more deposition chambers, this is considered a product-by-process limitation. "Even though product-by-process claims are limited by and defined by the process, determination of patentability is based on the product itself. The patentability of a product does not depend on its method of production. If the product in the product-by-process claim is the same as or obvious from a product of the prior art, the claim is unpatentable even though the prior product was made by a different process." In re Thorpe, 777 F.2d 695, 698, 227 USPQ 964, 966 (Fed. Cir. 1985).

Allowable Subject Matter

- 3. Claims 8 51 and 56 59 are allowed.
- 4. Claims 2, 3, 7, 17, 18, 20, 53 and 55 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.

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Response to Arguments

5. Applicant's arguments filed March 15, 2006 have been fully considered but they are not persuasive.

6. In response to applicant's argument that the references fail to show certain features of applicant's invention, it is noted that the features upon which applicant relies (i.e., the first low-dielectric constant material sub-layer formed over the etch stop layer) are not recited in the rejected claim(s). Although the claims are interpreted in light of the specification, limitations from the specification are not read into the claims. See *In re Van Geuns*, 988 F.2d 1181, 26 USPQ2d 1057 (Fed. Cir. 1993). Claim 1 only requires that the first low-dielectric constant material sub-layer be formed over the substrate.

Conclusion

7. **THIS ACTION IS MADE FINAL.** Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Douglas W. Owens whose telephone number is 571-272-1662. The examiner can normally be reached on Monday-Friday.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie C. Lee can be reached on 571-272-1732. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Douglas W Owens Primary Examiner Art Unit 2811

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